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(54) Title: ASSEMBLY AND METHOD FOR TESTING INTEGRATED CIRCUIT DEVICES

(57) Abstract

A testing assembly (10), and an associated method, for testing an integrated circuit device (12). The testing assembly (10) is capable of testing an integrated circuit device (12) having a large number of input and output terminals formed of either single-ended terminals (16) or differential terminals (20, 22). Static testing, both functional and parametric, can be performed upon the integrated circuit device (12). Additionally, dynamic testing of the integrated circuit device (12), even integrated circuit devices operable at high frequencies, is possible through operation of the testing assembly (10). Test signals are applied by way of signal rails (54, 56, 58) to the device (12) undergoing testing. A test signal response indicator (78) is coupled to observe responses to the test signals.

